BRIGHTEK

BRIGHTEK (EUROPE) LIMITED

Brighten Up The World With LED !

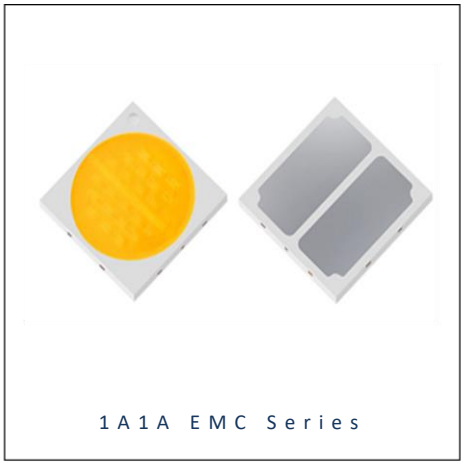
ISO/TS 16949:2009 BS EN ISO 14001:2004 QC 080000 IECQ HSPM

PRODUCT DATASHEET

- ► EMC 2-PIN SMD
- ► 1A1A 0.8t (10x10mm)
- ► Warm White (2700K)

Release Date: 26 April 2018 Version: A1.1

N0W45S56



1A1A EMC Series

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RoHS Compliant

FEATURES:

- **Package:** Top View EMC Package
- **Forward Current:** 400mA
- **Forward Voltage (typ.):** 37.8V
- **Luminous Flux (typ.):** 1750lm@400mA
- **Colour:** Warm White
- **Colour Temperature (CCT):** 2700K
- **Viewing angle:** 120°
- **Materials:**
  - Die: InGaN
  - Resin: Silicon (Yellow Diffused)
  - Package: EMC
- **Operating Temperature:** -40~+105°C
- **Storage Temperature:** -40~+100°C
- **Electrostatics Discharge:** 5000V
- **Grouping parameters:**
  - Forward Voltage
  - Luminous Flux
  - CIE Chromaticity
- **Soldering methods:** Reflow Soldering
- **MSL Level:** MSL3 according to J-STD020
- **Packing:** 16mm tape with Max.800/reel, ø178mm (7.5'')

APPLICATIONS:

- General Lighting
- Portable Lighting
- Commercial Lighting
- Indoor Lighting
- Backlight for LCD

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C, RH=60%)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I_F	480	mA
Pulse Forward Current (Duty 1/10, width≤100μS)	I_{PF}	640	mA
Power Dissipation	P_D	18.7	W
Reverse Voltage	V_R	5	V
Reverse Current @10V	I_R	10	μA
Junction Temperature	T_j	125	°C
Electrostatic Discharge	ESD	5000	V
Thermal Resistance (Junction to Solder Point)	R_{THJS}	1	°C/W
Operating Temperature	T_{OPR}	-40~+105	°C
Storage Temperature	T_{STG}	-40~+100	°C
Soldering Temperature	T_{SOL}	230 or 260 for 10S	°C
Colour Rendering Index	CRI	80	---

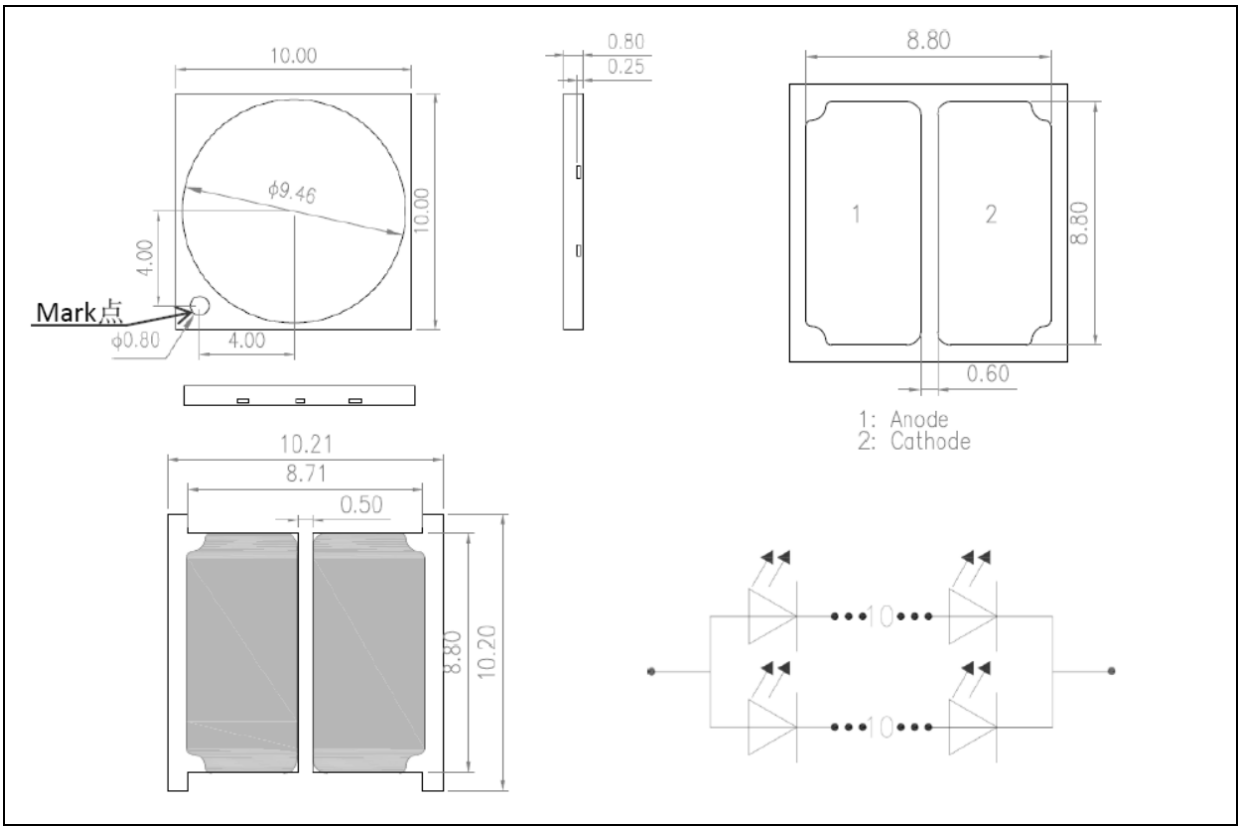
Electrical & Optical Characteristics (Ta=25°C, RH=60%)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	36	37.8	40	V	I_F=400mA
Luminous Flux	Φ_V	1600	1750	---	lm	I_F=400mA
Chromaticity Coordinates	X	---	0.4620	---	---	I_F=400mA
	Y	---	0.4145	---		
Colour Temperature	CCT	2580	2725	2870	K	I_F=400mA
Viewing Angle	$2\theta_{1/2}$	---	120	---	deg	I_F=400mA

1. Luminous flux (Φ_V) ±10%, Forward Voltage (V_F) ±0.1V

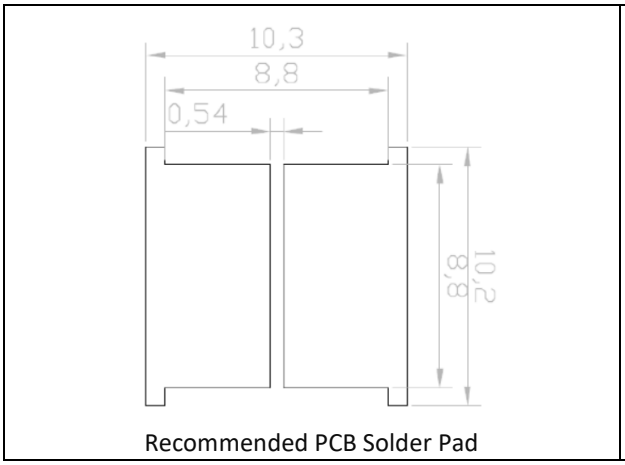
OUTLINE DIMENSION:

Package Dimension:

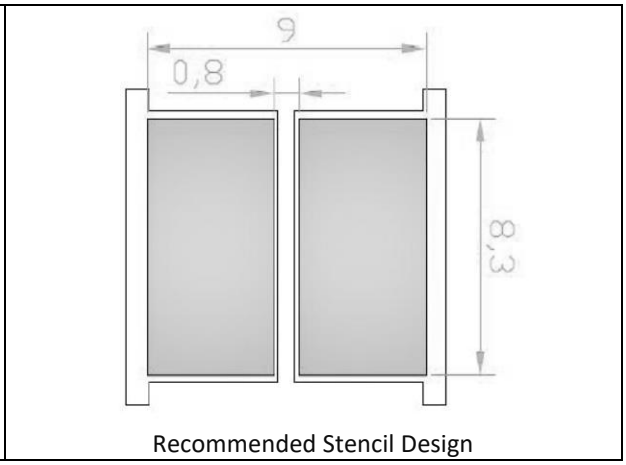


1. All dimensions are in millimetre (mm).
2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



Recommended PCB Solder Pad



Recommended Stencil Design

1. Dimensions are in millimetre (mm).
2. Tolerance ±0.1mm with angle tolerance ±0.5°.

BINNING GROUPS:

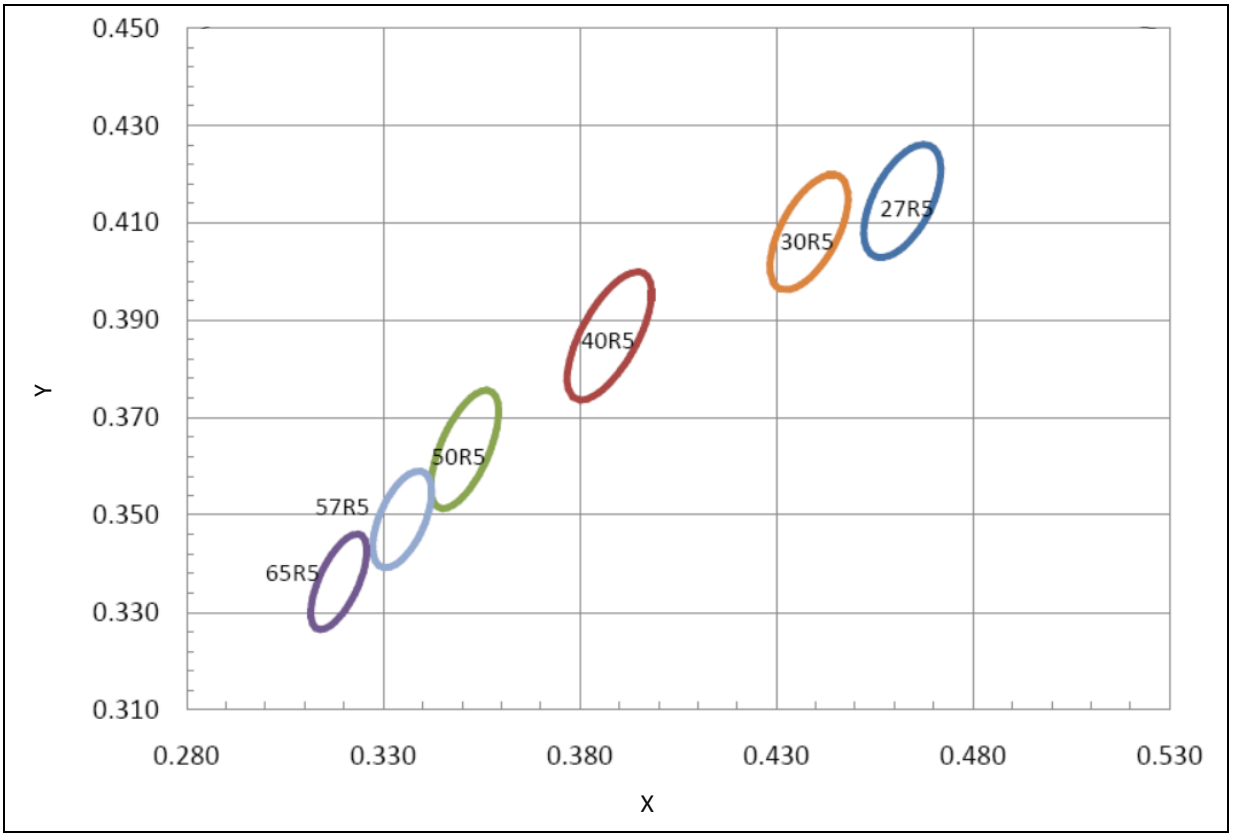
Forward Voltage Classifications (I_F = 400mA):

Code	Min.	Max.	Unit
6K	34	36	V
6L	36	38	
6M	38	40	

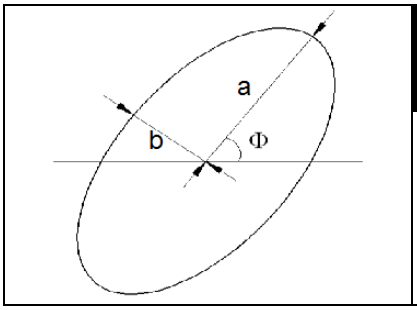
Luminous Flux Classifications (I_F = 400mA):

Code	Min.	Max.	Unit
3R	1650	1800	lm
3S	1800	1950	
3T	1950	2100	
3W	2100	2250	

CIE CHROMATICITY DIAGRAM:



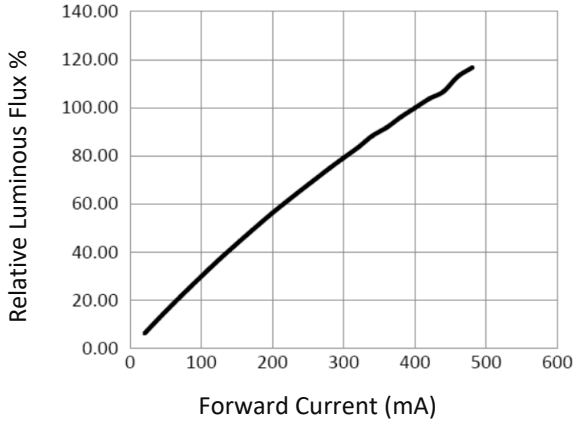
Chromaticity Coordinates Classifications (I_F = 400mA):



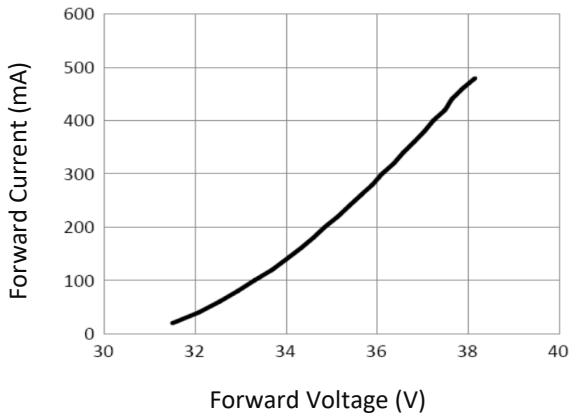
Code	Centre		Radius		Angle
	X	Y	a	b	Φ
27R5	0.4620	0.4145	0.01350	0.00700	53.42

ELECTRO-OPTICAL CHARACTERISTICS:

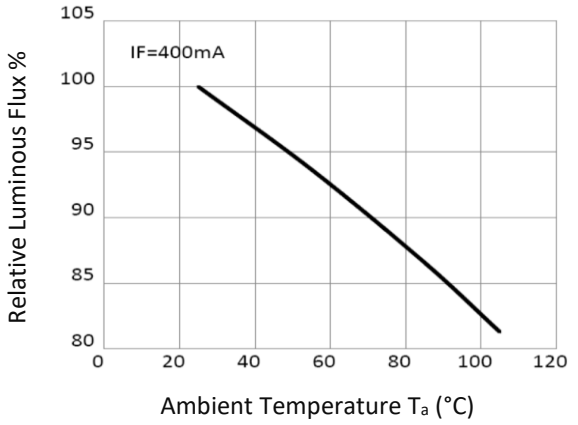
Relative Luminous Flux v.s. Forward Current



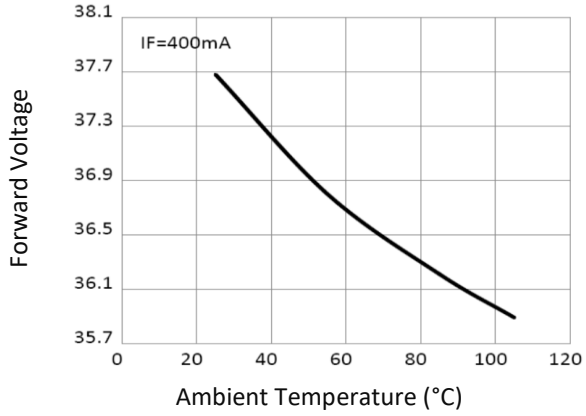
Forward Current v.s. Forward Voltage



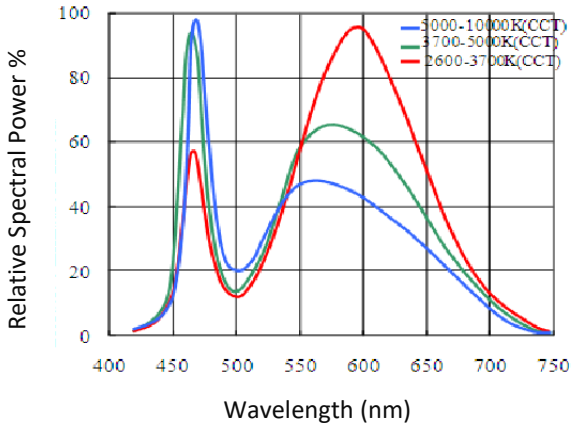
Relative Luminous Flux v.s. Ambient Temp.



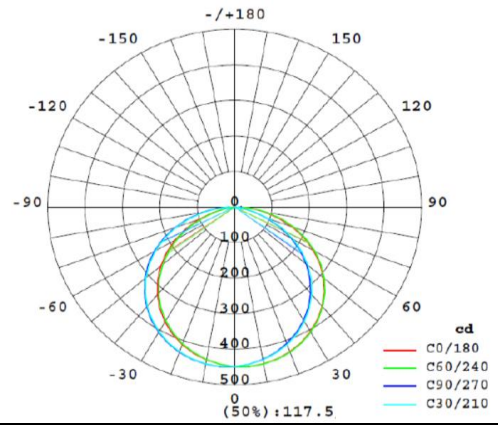
Forward Voltage v.s. Ambient Temp.

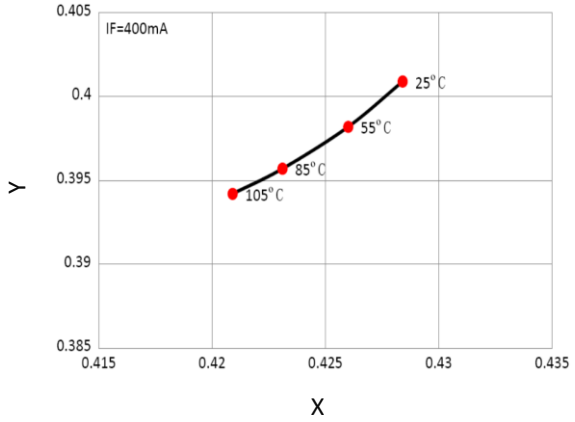
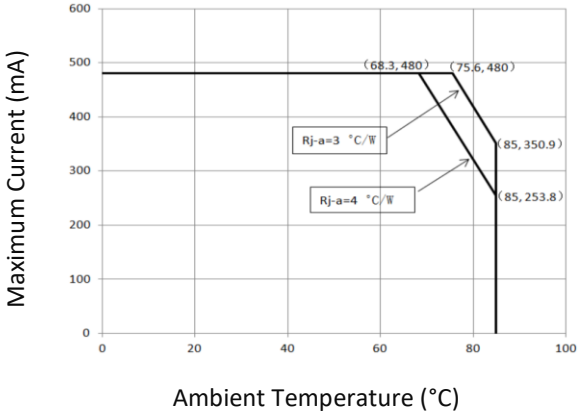


Relative Spectral Power v.s. Wavelength



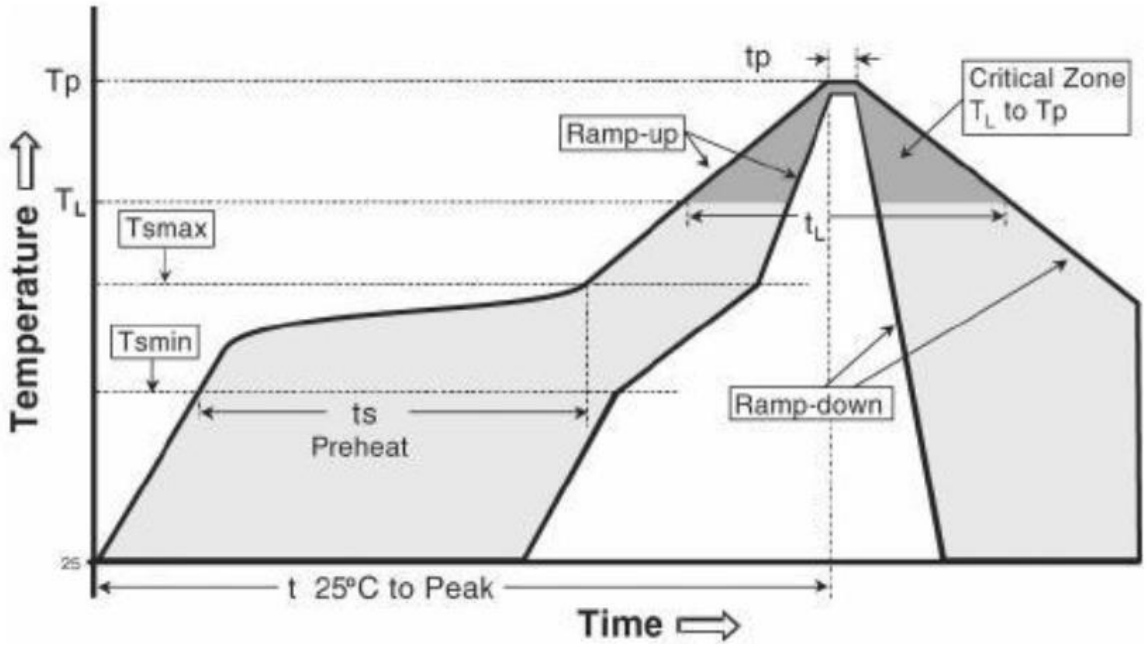
Directive Radiation



Ambient Temperature v.s. CIE X, Y Shift	Forward Current Derating Curve
	

RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:



Temperature Min. (T_{smin})	150°C
Temperature Max. (T_{smax})	200°C
Period from T_{smin} to T_{smax}	60-120 seconds
Ramp-up Rate (T_L to T_P)	Max. 3°C/second
Liquidous Temperature (T_L)	217°C
Time Maintained above T_L	60-150 seconds
Peak Package Temperature (T_P)	Max. 260°C
Time within 5°C of the Specified Classification Temperature T_C	Max. 30 seconds
Ramp-down Rate (T_P to T_L)	Max. 6°C/second
Time from 25°C to Peak Temperature	Max. 8 mins

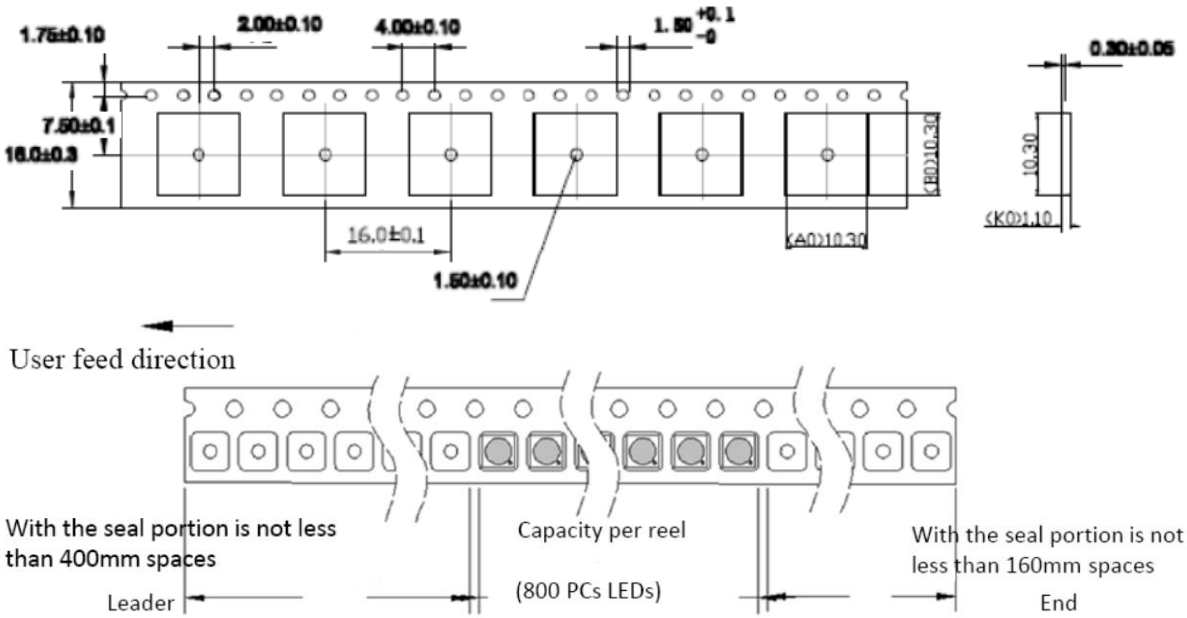
Note:

1. Maximum reflow soldering: 2 times.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.
3. Recommended soldering temperature: 230°C. The maximum soldering temperature should be limited to 260°C for max. 10seconds.

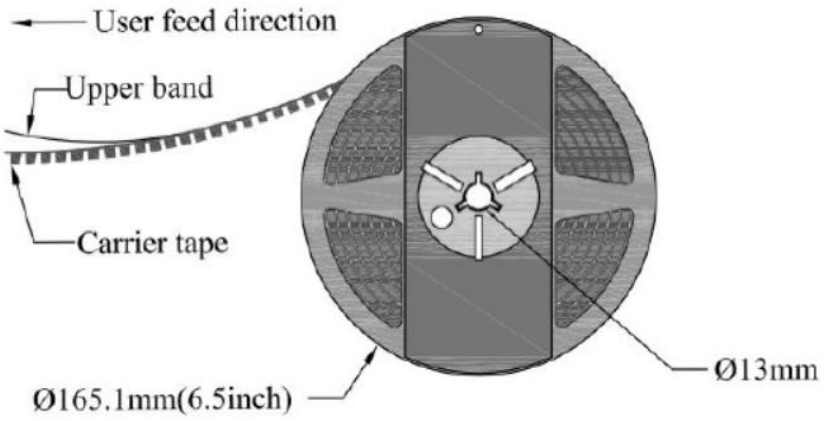
PACKING SPECIFICATION:

Reel Dimension:

Max.800pcs/reel



1. Cumulative Tolerance: Cumulative Tolerance/10 pitches to be ±0.2mm
2. Adhesion Strength of Cover Tape Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10˚ to the carrier tape.



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

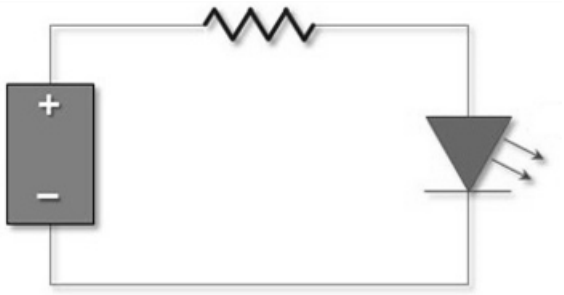
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 15hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	15/07/2016	Datasheet set-up.
A1.1	26/04/2018	New datasheet format.